ABSTRACT

Provided are a stamp preventing a fine structure from sticking to a surface of a stamp other than a holding portion thereof, and suppressing, from the stamp, a fall of a fine structure unintendedly sticking to such a surface, a holding portion for the stamp, a transfer method by such a stamp, a manufacturing method of an electric/electronic application product utilizing such a transfer method, and a manufacturing method of a display. A stamp 100 is for transferring a fine structure 200 and includes a base portion 1 formed on a substrate 10, a holding portion 2 formed on the base portion 1, and including a holding surface 21 for holding the fine structure 200, and a sticking suppressing portion 3 formed around the holding portion 2 on the base portion 1, and including a plurality of convexities 4 each including a sticking suppressing surface 41 with a lower

height than the holding surface 21. The sticking suppressing portion 3 is formed so as to have, when the fine structure 200 sticks thereto, adhesive force that does not allow the fine structure 200 to fall by force that is smaller than or equal to the own weight.